

Features

Collector Current: I_C=-0.6A

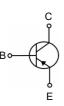
• Power Dissipation of 300mw



SOT-23

Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
MMBT4403	SOT-23	2T	3000



Maxmim Ratings (Ta=25 unless otherwise noted)

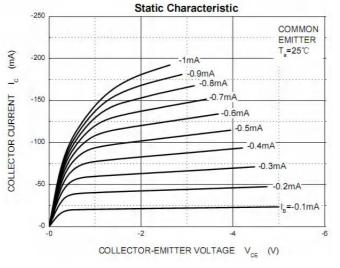
Parameter	Symbol	Limit	Unit
Collector-Base Voltage	V _{CBO}	-40	V
Collector-Emitter Voltage	V _{ceo}	-40	V
Emitter-Base Voltage	V _{EBO}	-5	V
Collector Current	I _c	-600	mA
Collector Power Dissipation	P _c	300	mW
Thermal Resistance From Junction To Ambient	R _{OJA}	417	°C/W
Junction Temperature	T _j	150	°C
Storage Temperature	T _{stg}	-55∼+150	°C

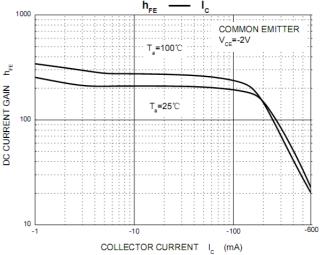


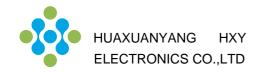
Electrcal Charcteristics (Ta=25 unless other wise specified)

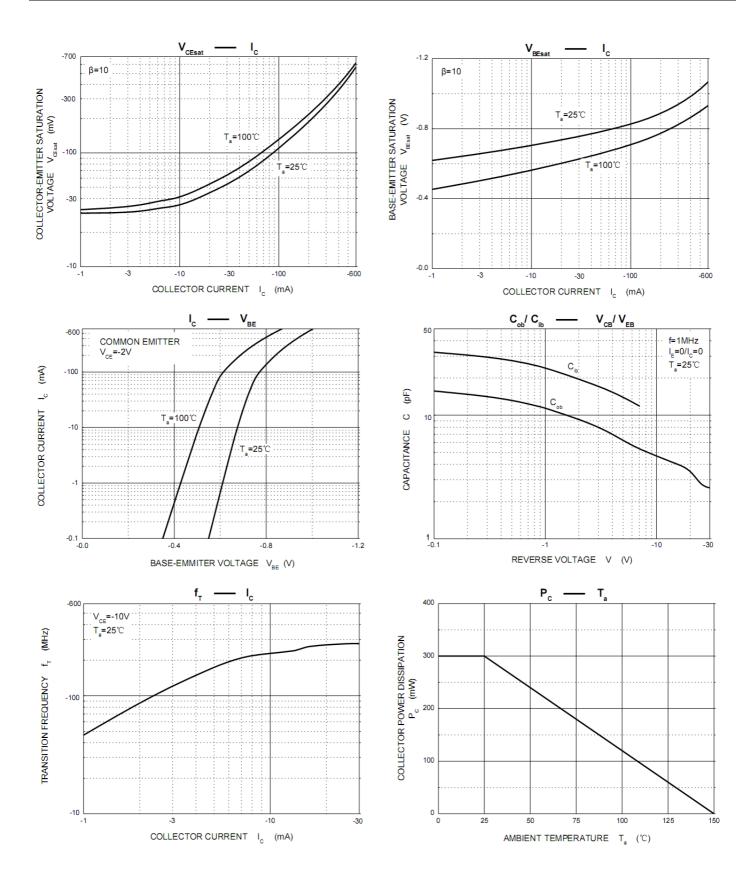
Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
Collector-base breakdown voltage	V _{(BR)CBO}	I _C =-100μA,I _E =0	-40			V
Collector-emitter breakdown voltage	V _{(BR)CEO}	I _C =-1mA,I _B =0	-40			V
Emitter-base breakdown voltage	$V_{(BR)EBO}$	I _E =-100μA ,I _C =0	-5			V
Collector cut-off current	I _{CBO}	V _{CB} =-35V,I _E =0			-0.1	μA
Collector cut-off current	I _{CEX}	Vce=-35V, VBE=0.4V			-0.1	μA
Emitter cut-off current	I _{EBO}	V _{EB} =-4V,I _C =0			-0.1	μA
	h _{FE1}	V _{CE} =-1V, I _C =-0.1mA	30			
	h _{FE2}	V _{CE} =-1V, I _C =-1mA	60			
DC current gain	h _{FE3}	V _{CE} =-1V, I _C =-10mA	100			
	h _{FE4}	V _{CE} =-2V, I _C =-150mA	100		300	
	h _{FE5}	V _{CE} =-2V, I _C =-500mA	20			
Collector-emitter saturation voltage	V _{CE(sat)}	I _C =-150mA,I _B =-15mA			-0.4	V
Collector-enfitter saturation voltage		I _C =-500mA,I _B =-50mA			-0.75	V
Door and the most west on west on	V _{BE(sat)}	I _C =-150mA,I _B =-15mA			-0.95	V
Base-emitter saturation voltage		I _C =-500mA,I _B =-50mA			-1.3	V
Transition frequency	f⊤	V _{CE} =-10V, I _C =-20mA,f =100MHz	200			MHz
Delay time	t _d	Vcc=-30V, VBE(off)=-0.5V			15	ns
Rise time	t _r	Ic=-150mA , Ів1=-15mA			20	ns
Storage time	t _s	Vcc=-30V, Ic=-150mA			225	ns
Fall time	t _f	I _{B1} =I _{B2} =-15mA			60	ns

Typical Characteristics

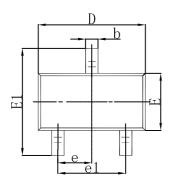


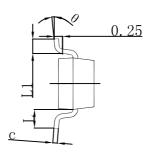


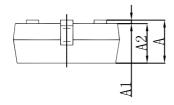




SOT-23 Package Outline Dimensions

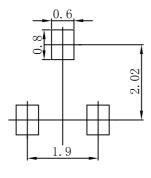






Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
Α	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
С	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
е	0.950	TYP	0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022 REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

SOT-23 Suggested Pad Layout



- Note:
 1.Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.
 3.The pad layout is for reference purposes only.



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